

SH8KE5

100V Nch+Nch Power MOSFET

V _{DSS}	100V
R _{DS(on)} (Max.)	200mΩ
I _D	±2.5A
P _D	2.0W

Features

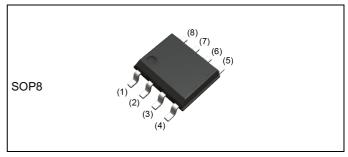
- 1) Low on resistance
- 2) Small Surface Mount Package (SOP8)
- 3) Pb-free plating; RoHS compliant
- 4) Halogen Free
- 5)100% Rg and UIS tested

Application

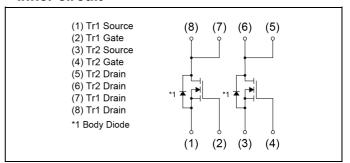
Switching

Motor drives

Outline



•Inner circuit



Packaging specifications

Туре	Packing	Embossed Tape
	Reel size (mm)	330
	Tape width (mm)	12
	Quantity (pcs)	2500
	Taping code	TB1
	Marking	SH8KE5

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified) < Tr1 and Tr2>

Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	100	V
Continuous drain current	I _D	±2.5	Α
Pulsed drain current	I _{DP} *1	±10	А
Gate - Source voltage	V _{GSS}	±20	V
Avalanche current, single pulse	I _{AS} *2	2.5	Α
Avalanche energy, single pulse	E _{AS} *2	0.50	mJ
	P _D *3	2.0	10/
Power dissipation (total)	P _D *4	1.4	W
Junction temperature	T _j	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Darameter	Cymbol	Values			Lloit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal registance innetion, ambient (total)	R_{thJA}^{*3}	-	-	62.5	°C/W
Thermal resistance, junction - ambient (total)	R _{thJA} *4	-	-	89.2	C/VV

● Electrical characteristics (T_a = 25°C) < Tr1 and Tr2>

		0 19	Values			11.20	
Parameter	Symbol	Conditions	Min.	Min. Typ. Max.		Unit	
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{GS} = 0V$, $I_D = 1mA$	100	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I _D = 1mA referenced to 25°C	-	67	-	mV/°C	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 100V, V _{GS} = 0V	-	-	1	μA	
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	1	-	±100	nA	
Gate threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 1mA$	1.0	-	2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I _D = 1mA referenced to 25°C	-	-4.0	-	mV/°C	
Static drain - source	D *5	V _{GS} = 10V, I _D = 2.5A	-	154	200	0	
on - state resistance	R _{DS(on)} *5	V _{GS} = 4.5V, I _D = 2.5A	-	197	295	mΩ	
Gate resistance	R_G	-	-	2.6	-	Ω	
Forward Transfer Admittance	Y _{fs} *5	V _{DS} = 5V, I _D = 2.5A	1.6	-	-	S	

^{*1} Pw ≤ 10µs, Duty cycle ≤ 1%

^{*2} L \simeq 0.1mH, V_{DD} = 50V, R_G = 25 Ω , Starting T_j = 25 $^{\circ}$ C Fig.3-1,3-2

^{*3} Mounted on a ceramic board (30×30×0.8mm)

^{*4} Mounted on a Cu board (40×40×0.8mm)

^{*5} Pulsed

● Electrical characteristics (T_a = 25°C) < Tr1 and Tr2>

Daramatar	Current of	Conditions		Unit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C _{iss}	V _{GS} = 0V	-	90	-	
Output capacitance	C _{oss}	V _{DS} = 50V	-	25	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	4	-	
Turn - on delay time	t _{d(on)} *5	V _{DD} ≈ 50V,V _{GS} = 10V	-	6.0	-	
Rise time	t _r *5	I _D = 1.25A	-	6.0	-	
Turn - off delay time	t _{d(off)} *5	$R_L = 40\Omega$	-	13.0	-	ns
Fall time	t _f *5	$R_G = 10\Omega$	-	5.0	-	

● Gate charge characteristics (T_a = 25°C) < Tr1 and Tr2>

Darameter	Cumbal	Conditions -		Values			Unit
Parameter	Symbol			Min.	Тур.	Max.	Offic
Total mate about	Q_g^{*5}		V _{GS} = 10V	-	2.9	-	
Total gate charge		Qg	V _{DD} ≈ 50V		-	1.7	-
Gate - Source charge	Q _{gs} *5	I _D = 2.5A	V _{GS} = 4.5V	-	0.7	-	nC
Gate - Drain charge	Q _{gd} *5			-	0.5	-	

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

<Tr1 and Tr2>

Parameter	Symbol	Conditions		Unit			
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Continuous forward current	I _S	T _a = 25°C	-	1	1.67	^	
Pulse forward current	I _{SP} *1	1 _a – 25 C	-	-	10	A	
Forward voltage	V _{SD} *5	V _{GS} = 0V, I _S = 1.67A	-	-	1.2	V	
Reverse recovery time	t _{rr} *5	I _S = 2.5A, V _{GS} = 0V	-	28	-	ns	
Reverse recovery charge	Q _{rr} *5	di/dt = 100A/µs	-	32	-	nC	

Power Dissipation: P_D/P_{Dmax}. [%]

• Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

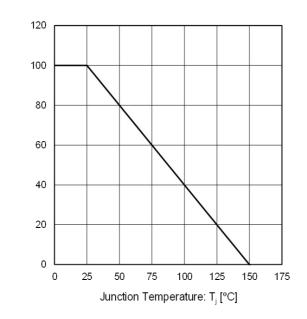
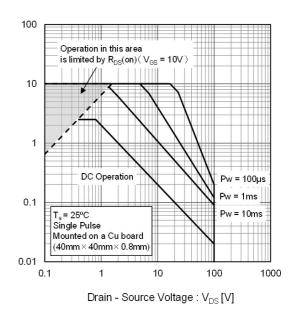


Fig.2 Maximum Safe Operating Area



Drain Current : I_D [A]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

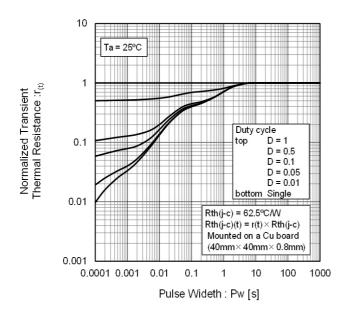
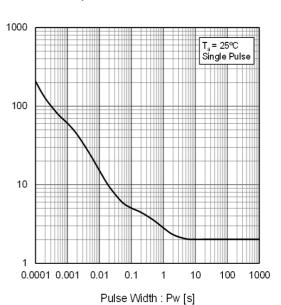


Fig.4 Single Pulse Maximum Power Dissipation



Peak Transient Power: P[W]

Drain Current : I_D [A]

• Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)

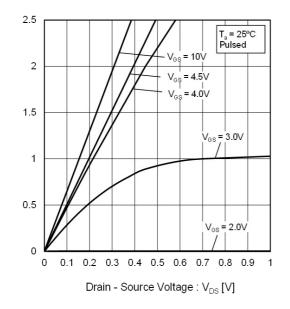


Fig.6 Typical Output Characteristics(II)

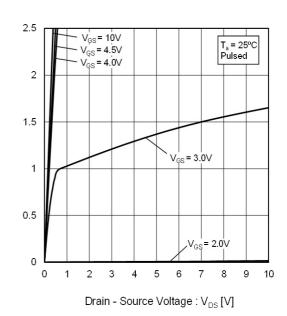
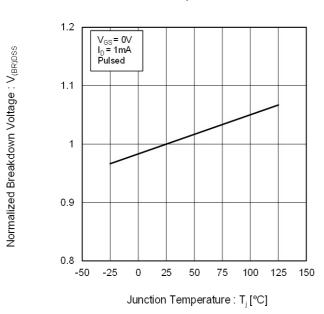


Fig.7 Normalized Breakdown Voltage vs. Junction Temperature



Drain Current: I_D [A]

• Electrical characteristic curves

Fig.8 Typical Transfer Characteristics

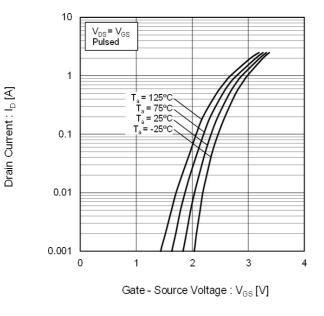


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

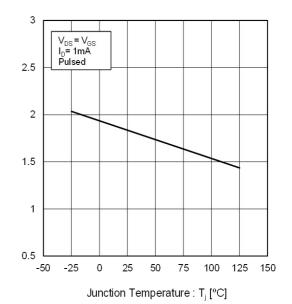
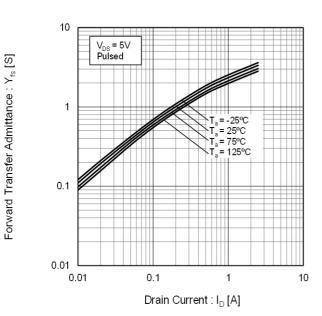


Fig.10 Forward Transfer Admittance vs.
Drain Current



Gate Threshold Voltage : $V_{GS(th)}$ [V]

Drain Current Dissipation: Ip/Ipmax. [%]

• Electrical characteristic curves

Fig.11 Drain Current Derating Curve

120
100
80
60
40
20
0 25 50 75 100 125 150

Junction Temperature : T_i [°C]

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

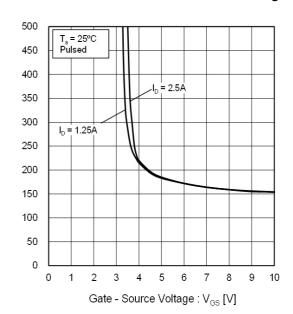
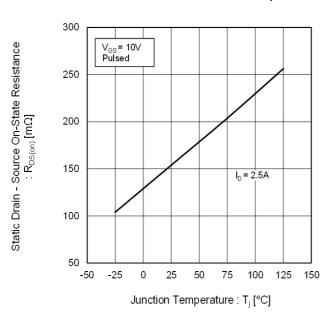


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature



Static Drain - Source On-State Resistance

• Electrical characteristic curves

Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

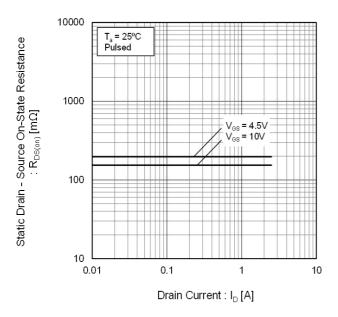


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

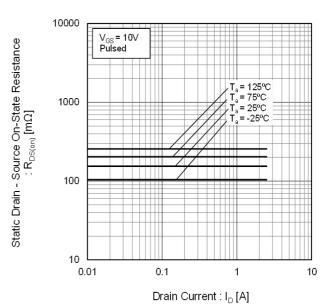
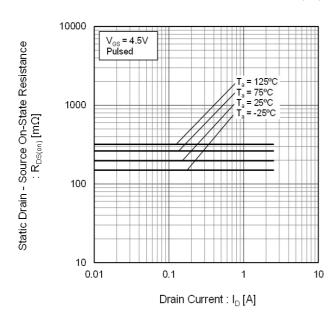


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)



Capacitance : C [pF]

Gate - Source Voltage : $V_{\mathbb{GS}}$ [V]

• Electrical characteristic curves

Fig.17 Typical Capacitances vs.

Drain - Source Voltage

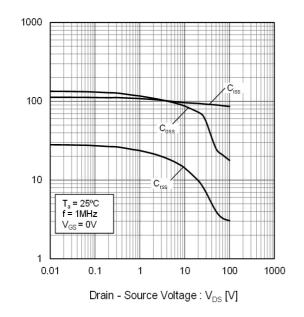
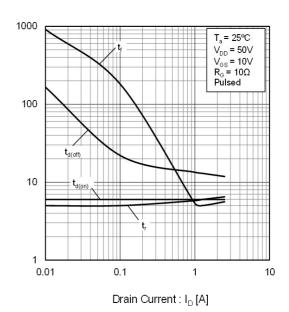


Fig.18 Switching Characteristics



Switching Time : t [ns]

Fig.19 Typical Gate Charge

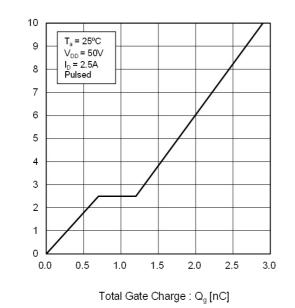
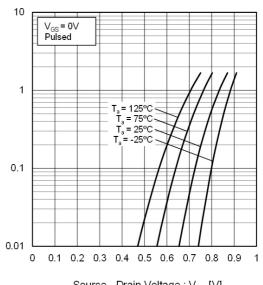


Fig.20 Source Current vs.

Source Drain Voltage



Source Current : Is [A]

• Measurement circuits < It is the same for the Tr1 and Tr2>

Fig.1-1 Switching Time Measurement Circuit

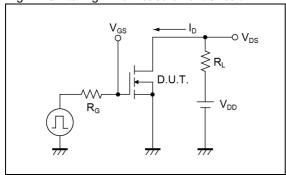


Fig.2-1 Gate Charge Measurement Circuit

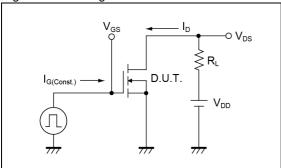


Fig.3-1 Avalanche Measurement Circuit

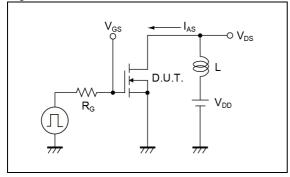


Fig.1-2 Switching Waveforms

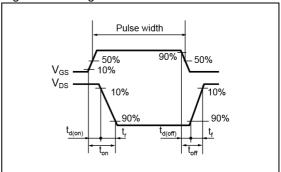


Fig.2-2 Gate Charge Waveform

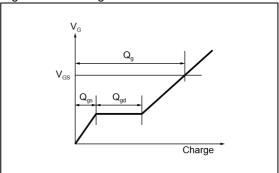
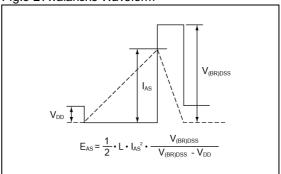


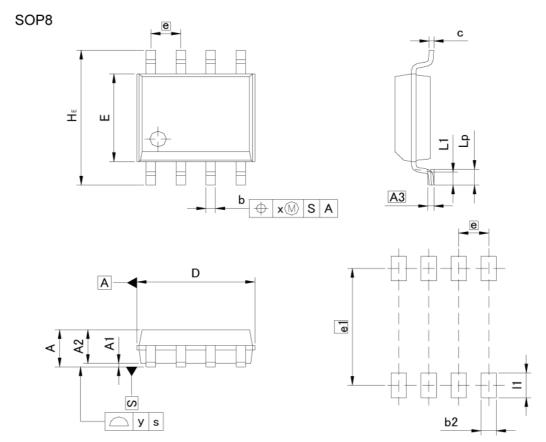
Fig.3-2 Avalanche Waveform



Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	-	1.75	-	0.069	
A1	0.	15	0.0	06	
A2	1.40	1.60	0.055	0.063	
A3	0.2	25	0.0	10	
b	0.30	0.50	0.012	0.020	
С	0.10	0.30	0.004	0.012	
D	4.80	5.20	0.189	0.205	
Е	3.75	4.05	0.148	0.159	
е	1.2	27	0.050		
HE	5.70	6.30	0.224	0.248	
L1	0.40	0.60	0.016	0.024	
Lp	0.65	0.85	0.026	0.033	
х	0.	15	0.0	06	
у	0.	10	0.004		
DIM	MILIM	ETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
b2	-	0.65	-	0.026	
e1	5.	15	0.2	03	
11	-	1.15	-	0.045	

Dimension in mm/inches



Notice

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JÁPAN	USA	EU	CHINA
CLASSⅢ	CL A C C TT	CLASS II b	CL ACCIII
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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